

# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

<b>Title of Invention</b>	Bond Pad Structure Comprising Multiple Bond Pads with metal Overlap						
Application Number :	09/927675						
Confirmation Number:	6524						
First Named Applicant:	Guy Perry						
Attorney Docket Number:	MTI-31471						
Art Unit:	2815						
Examiner:	Chris C Chu						
Search string:	( 4184909 or 5292624 or 4721689 ).pn						
<b>US Patent Documents</b>							
<b>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</b>							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	4184909	1980-01-22	Chang et al.		438	624
	2	5292624	1994-03-08	Wei		430	313
	3	4721689	1988-01-26	Chaloux et al.		438	618
<b>Signature</b>							
Examiner Name				Date			